LEADFRAME FOR PLASTIC-ENCAPSULATED SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE USING THE SAME, AND MANUFACTURING METHOD FOR THE LEADFRAME

Abstract of the Disclosure

Provided is a leadframe (1) of a copper alloy for plastic-encapsulated semiconductor device, in which a leadframe (1) material (copper alloy) can be prevented from delaminating from a molding plastic. The leadframe (1) comprises a film of the copper alloy, which is composed of copper and one or more metals selected from a group including silver, gold, platinum, and palladium, and is formed on the surface of the leadframe (1) material.

Figure 1A, 1B